

Front-End Electronics 2018

Thursday 24 May 2018

Invited Speaker: “Challenges and Research for High Density, Highly Integrated Microelectronic Packaging” (08:30-09:30)

-Conveners: David Danovitch

Invited Speaker: Quantum computing in silicon : Overview and opportunities in cryogenic front-end electronics
(10:50-11:50)

-Conveners: Michel Pioro Ladriere